and the

Exam.Code: 0932 Sub. Code: 6927

1108

B.E., (Electronics and Communication Engineering) Eighth Semester EC-814: MEMS and Microsystems

Time allowed: 3 Hours

Max. Marks: 50

NOTE: Attempt <u>five</u> questions in all, including Question No. I which is compulsory and selecting two questions from each Unit.

x-x-x

- I. Attempt the following:
 - a) Define MEMS and microsystems.
 - b) Compare actuation principles: Electrostatic and Piezoelectric.
 - c) Write four important properties of silicon as substrate material for MEMS.
 - d) Write an two differences between erfc and Gaussian profile of diffusion.
 - e) Explain in short about mechanical stresses experienced by surface micromachined MEMS devices. (5x2)

UNIT-I

- II. a) Write a comparison between microelectronics and Microsystems.
 - b) Discuss the scaling laws in electrostatic forces.

(2x5)

- III. a) Name the three principal signal transduction methods for micro-pressure sensor. Provide at least one major advantage and one disadvantage of each of the three methods.
 - b) Estimate the number of atoms per cubic centimeter of pure silicon. (2x5)
- IV. a) Estimate the associated changes in the acceleration 'a', time 't' and the power supply to actuate MEMS component if its weight is reduced by a factor of 10.
 - b) Discuss the working principle of an accelerometer. How microaccelerometer is different from macro-accelerometer. Also sketch the schematic structure of a microaccelerometer. (4,6)

P.T.O.

UNIT-II

- V. a) Explain the process of thermal oxidation for the growth of an oxide layer over silicon substrate.
 - b) Explain the difference between bulk and surface micromachining with the help of an example. (2x5)
- VI. a) Discuss the various steps involved in the production of a microcantilever structure with the help of surface micromachining.
 - b) Discuss the process of etching with respect to three principal planes of silicon substrate. (7,3)
- VII. a) Discuss the various design constraints for MEMS & Microsystems.
 - b) What is the principle sources of intrinsic stresses induced in the microsystems? (7,3)